178 Ball LPDDR3 Oscilloscope Component Interposer

178 Ball Discrete BGA Memory Device Support

- Optimal Analog Validation
- Use with Existing Embedded / Mobile designs
- Scope probe tips designed into the interposer
- Socket Design also available without a socket
- Support for LPDDR3 Memory devices
 - o X16/x32 data width
 - o 0.8mm X-Axis pitch, 0.65mm Y-Axis pitch



Premier Target Socketed Component Interposer Design

Optimal LPDDR3 validation requires analysis of the LPDDR3 signals, as seen by the memory components. This allows for the highest confidence that the signal captured are representative of the signals on the target. Nexus Technology component interposers allow for oscilloscope probing of the LPDDR3 signals extremely close to the memory components BGA solder balls.

Memory Component Interposer Installation

The process of attaching the interposer to your target has been greatly simplified using Nexus Technology's patented, high-bandwidth, component interposer sockets. These patented sockets remove the need to contract specialized rework houses to perform the installation. Instead, you can use standard BGA assembly practices to install the component interposer socket. Nexus Technology can perform the attachment service for a nominal fee.

Once the interposer socket is installed on the target, logic analyzer or oscilloscope interposers can be easily inserted or removed from the socket. Note that the interposer socket elevates the interposer above the adjacent components to provide the mechanical clearance necessary for easy probe attachment.

LPDDR3 BGA Component Installation

The interposer can be ordered with a second socket for easy BGA memory component installation and removal. These sockets allow for the quick swapping and testing of different memory components on the interposer.

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Oscilloscope Component Interposer Hardware

Connection to an oscilloscope is enabled by using oscilloscope memory component interposers. These controlled impedance; matched trace length interposers provide analog visibility using an oscilloscope. All signals are brought out to probe points that are designed to accommodate solder down probe tips. For more information, please see the Nexus Soldering Guide. Removable oscilloscope probe tips can also be used to easily move the oscilloscope probe between signals for quick and accurate measurement.



Oscilloscope Analog Validation

Filter software, available from Tektronix for use with select Tektronix oscilloscopes, removes the effect of the oscilloscope interposer. Although these interposers are designed to optimize signal integrity, this feature removes even the slightest effect the adapter has from the oscilloscope display.

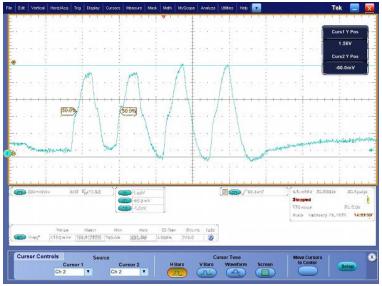


Figure 1: Strobe as seen using an oscilloscope component interposer

Nexus Technology's Component Interposer Advantages

Probed at the BGA Pads

The best place to probe to eliminate reflections associated with standard embedded LPDDR3 mid bus probing or other methods is at the FBGA pads. Interposers require no target footprints or special routing requirements that mid bus probing requires.

Use with Existing Embedded Designs

No need to change existing designs. Simply add the interposer to your embedded target with no redesign or added probe points.

Socket Design

The interposers are reusable. Once an interposer socket is installed, the interposer can be attached and removed by hand - allowing the interposer to be used on multiple targets quickly or allowing quick swapping of logic analyzer and oscilloscope interposers on the same target.

Easy to Install

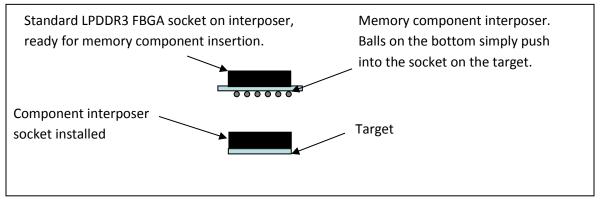
Just install the optional interposer socket by using industry standard BGA attachment methods, or by utilizing Nexus Technology's attachment service.

Interposer Retention to the Target

The interposer socket has four posts that are tack-soldered to four mounting holes on the interposer. This ensures that the interposer will not be mistakenly pulled off of the target.

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Attaching & Reusing Interposers



After pressing the interposer onto the socket, removable epoxy should be added to retain the interposer to the socket



Interposers designed for Nexus custom sockets do not need epoxy for retention

Product Dimensions

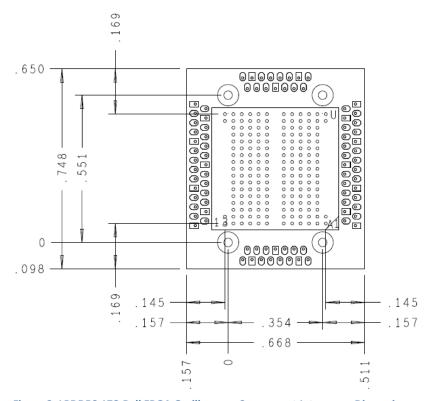


Figure 2: LPDDR3 178-Ball FBGA Oscilloscope Component Interposer Dimensions

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Product Configuration Tables

LPDDR3 178-ball Oscilloscope Interposers

Nomenclature		Component Sockets Included
NEX-LP3MP178BSC	Oscilloscope	No
NEX-LP3MP178BSCSK	Oscilloscope	Yes

Optional Additional LPDDR3 178 Ball Component Interposer Sockets

Nomenclature	Solder Balls Added	Quantity of Sockets
NEX-LP3178BGASKBA	Yes	1
NEX-LP3178BGASKBA-3	Yes	3

Optional Attachment Service

Nexus offers an optional Attachment Service. We will remove the requested memory from your target/DIMM, install the interposer, re-ball and re-attach the memory onto the interposer.

Further Information

Please contact us by telephone, email or mail as listed below. Email is preferred. Normal business hours are 9:00 - 5:00 EST.

Telephone 877-595-8116

International 603-329-3083

Fax 877-595-8118

Address 78 Northeastern Blvd. Unit 2 Nashua, NH 03062

Technical Support techsupport@nexustechnology.com

Quote Requests quotes@nexustechnology.com

General Information support@nexustechnology.com

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